

What is claimed is:

1. A cooling assembly for at least one board, the at least one board suitable for accepting a plurality of components including a first component, the cooling assembly comprising:
 - a passage;
 - a fan suitable for passing air through the passage; and
 - an isolation assembly for generally enclosing heat generated from the first component, the isolation assembly in communication with the passage.
2. The cooling assembly of claim 1, and further comprising an alternate passage in communication with the isolation assembly.
3. The cooling assembly of claim 2, wherein the alternate passage includes a conduit in communication with the isolation assembly.
4. The cooling assembly of claim 1, and further comprising a heat sink operably coupled to the first component.
5. The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.
6. The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

7. A computer system, comprising:
- a computer case having a board suitable for accepting a plurality of components comprising at least one processor; and
 - a cooling assembly for the board, the cooling assembly comprising:
 - a passage;
 - a fan suitable for passing air through the passage; and
 - an isolation assembly for generally enclosing heat generated from the at least one processor, the isolation assembly in communication with the passage.
8. The computer system of claim 7, wherein the cooling assembly further comprises an alternate passage in communication with the isolation assembly.
9. The computer system of claim 8, wherein the alternate passage includes a conduit in communication with the isolation assembly.
10. The computer system of claim 7, further comprising a heat sink operably coupled to the processor.
11. The computer system of claim 7, wherein the plurality of components are enclosed within a computer case, and the air is drawn from outside the computer case.
12. The computer system of claim 7, wherein the plurality of components are enclosed within a computer case, and the air is drawn from within the computer case.
13. The computer system of claim 11, wherein at least 80 percent of the air drawn from outside the computer case is exhausted back to outside the computer case.

14. The computer system of claim 11, wherein a significant amount of the air drawn from outside the computer case is exhausted back to outside the computer case.
15. The computer system of claim 12, wherein at least 80 percent of the air drawn from outside the computer case is exhausted back to outside the computer case.
16. The computer system of claim 12, wherein a significant amount of the air drawn from outside the computer case is exhausted back to outside the computer case.
17. The computer system of claim 7, wherein the cooling assembly is detachable from the computer case.
18. The computer system of claim 7, wherein the isolation assembly is electromagnetically isolated for a particular processor.
19. A method for dissipating heat, the method comprising the steps of:
 - providing an isolation assembly in a computer case having therein a processor and a heat sink attached to the processor;
 - drawing air from outside the isolation assembly into the isolation assembly containing the processor and heat sink;
 - passing the air over the processor and the heat sink; and
 - directing the air through the isolation assembly to outside of the computer case.
20. The method as specified in claim 19, and further comprising the step of directing all of the air to outside of the computer case.

21. The method as specified in claim 19, and further comprising the step of directing at least 80 percent of the air to outside of the computer case.
22. The method as specified in claim 19, wherein the air drawn from outside of the isolation assembly comes from the outside of the computer case.
23. The method as specified in claim 19, wherein the air drawn from outside of the isolation assembly comes from the inside of the computer case.
24. A processor assembly, comprising:
a processor module capable of connecting a processor and a heat sink for the processor;
an enclosure substantially isolating the processor module;
a fan assembly for blowing air across the processor module;
a plurality of openings in the enclosure;
a processor connection socket connection for the processor module; and
a power connection for the fan assembly.
25. The processor assembly of claim 24, wherein the processor assembly is removably attachable to a computer case without opening the computer case.
26. The processor assembly of claim 24, wherein the enclosure is specifically sized to the a particular processor.
27. The processor assembly of claim 24, wherein the enclosure is electromagnetically isolated for a particular processor.

28. A computer case, comprising:
a main body having a plurality of connectors for peripheral components;
a detachable processor assembly, comprising:
a processor module capable of connecting a processor and a heat sink for the processor;
an enclosure substantially isolating the processor module from the main body;
a fan assembly for blowing air across the processor module;
a plurality of openings in the enclosure;
a processor connection socket connection for the processor module; and
a power connection for the fan assembly.
29. The computer case of claim 28, wherein the plurality of openings vent directly outside the main body.
30. The computer case of claim 28, wherein the enclosure is specifically sized to the a particular processor.
31. The computer case of claim 28, wherein the enclosure is electromagnetically isolated for a particular processor.